

# SOT1114-1

plastic thermal enhanced very very thin quad flat package;  
no leads; 56 terminals; resin based; body 7 x 7 x 0.7 mm

8 February 2016

Package information

## 1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	HWQFN56R
Package type industry code	HWQFN56R
Package style descriptive code	HWQFN (thermal enhanced very very thin quad flatpack; no leads)
Package style suffix code	R (resin based)
Package body material type	P (plastic)
IEC package outline code	---
JEDEC package outline code	---
JEITA package outline code	---
Mounting method type	S (surface mount)
Issue date	7-10-2008

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		6.9	-	7	7.1	mm
E	package width		6.9	-	7	7.1	mm
A	seated height		0.65	-	0.7	0.8	mm
n <sub>2</sub>	actual quantity of termination		-	-	56	-	

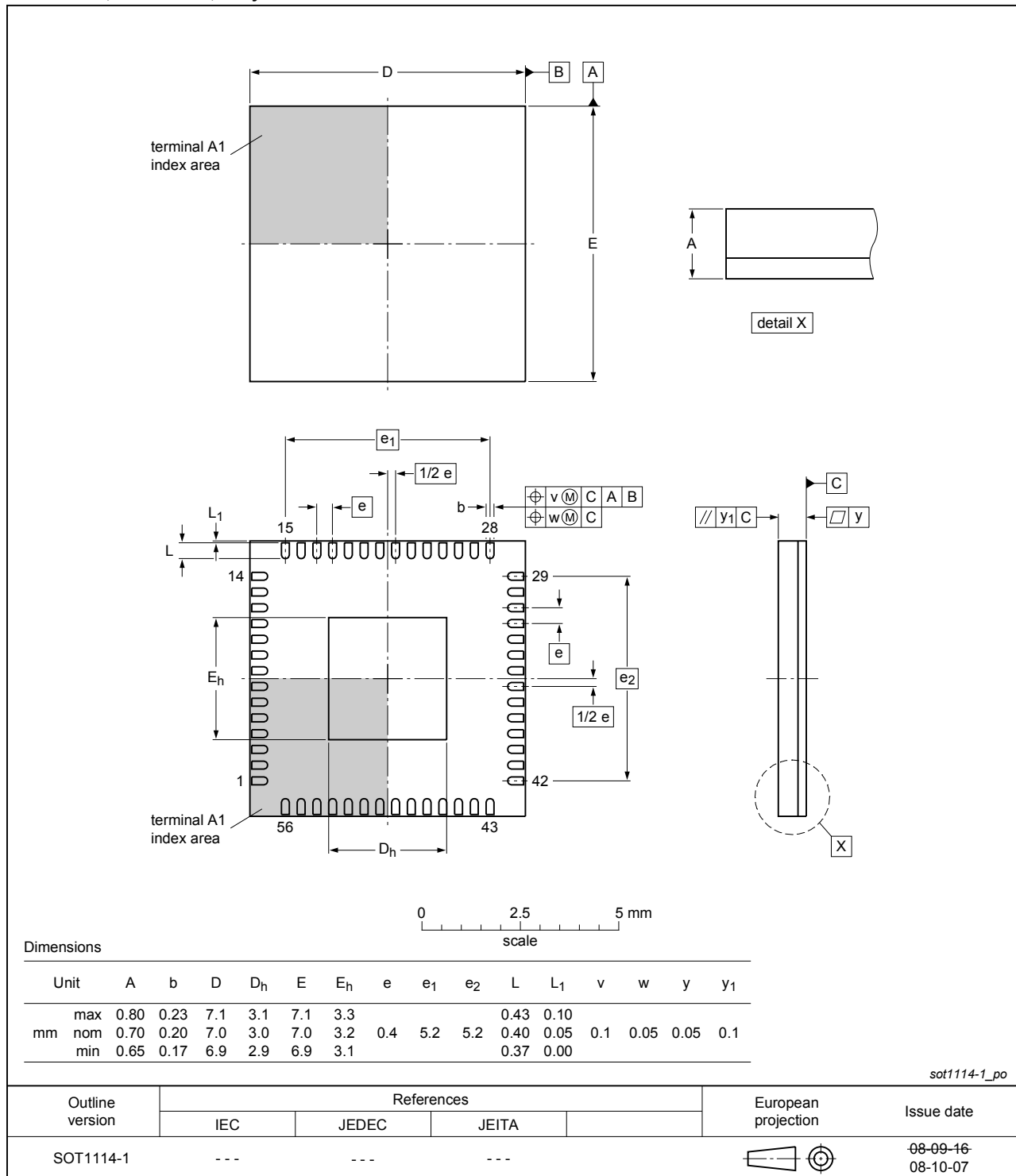


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## 2. Package outline

**HWQFN56R: plastic thermal enhanced very very thin quad flat package; no leads; 56 terminals; resin based; body 7 x 7 x 0.7 mm**

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**Fig. 1. Package outline HWQFN56R (SOT1114-1)**

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### 3. Legal information

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